

10 | 669, 901

| Ref #         | Hits           | Search Query  | DBs  | Default Operator | Plurals       | Time Stamp                  |
|---------------|----------------|---|--|------------------|---------------|-----------------------------|
| <del>L1</del> | <del>698</del> | <del>((MEMS) adj device) and ((MEMS) adj structure)</del>         | <del>US-PGPUB;<br/>USPAT;<br/>EPO; JPO;<br/>DERWENT;<br/>IBM_TDB</del> | <del>OR</del>    | <del>ON</del> | <del>2005/03/19 18:20</del> |
| L2            | 2              | (semiconductor adj integrated adj circuit) and (thermal adj bond) | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB                | OR               | ON            | 2005/03/19 18:21            |
| L3            | 104            | (integrated adj circuit) and (thermal adj bond)                   | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB                | OR               | ON            | 2005/03/19 18:24            |
| L4            | 398            | package and (thermal adj bond)                                    | US-PGPUB;<br>USPAT;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB                | OR               | ON            | 2005/03/19 18:24            |